LDIP1570-2520

FR Diplexer

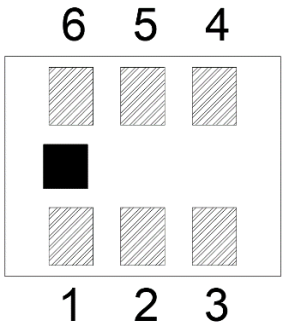
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

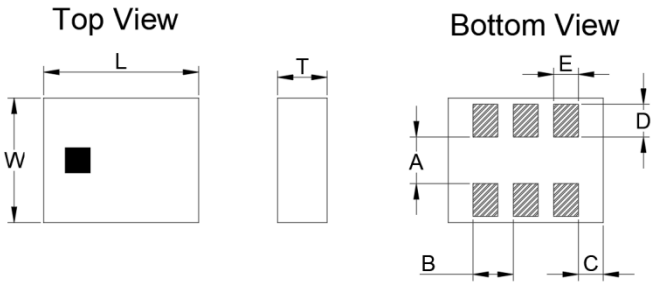
NO.	Parameter		SPEC	
			25℃	-40~+85℃
1	Low_Band Insertion Loss (dB)	450~960 MHz	0.45 dB	0.50 dB
		960~1427 MHz	0.45 dB	0.50 dB
		1427~1710 MHz	0.45 dB	0.50 dB
		1710~1990 MHz	0.70 dB	0.80 dB
		1990~2025 MHz	0.75 dB	0.85 dB
		2025~2110 MHz	1.40 dB	1.55 dB
		2110~2170 MHz	1.90 dB	2.30 dB
		2170~2200 MHz	2.80 dB	4.20 dB
	High_Band Insertion Loss (dB)	2300~2350 MHz	1.90 dB	2.40 dB
		2350~2400 MHz	0.95 dB	1.10 dB
		2400~2500 MHz	0.80 dB	0.90 dB
		2500~2690 MHz	0.65 dB	0.75 dB
2	Low_Band Return Loss (dB)	450~2200	10 dB	-
	High_Band Insertion Loss (dB)	2300~2690	10 dB	-
3	Low_Band Attenuation (dB)	2300~2350 MHz	10 dB	-
		2350~2690 MHz	10 dB	-
		3300~4200 MHz	18 dB	-
		4400~5000 MHz	20 dB	-
		5150~5925 MHz	20 dB	-
	High_Band Attenuation (dB)	450~960 MHz	16 dB	-
		1427~1710 MHz	20 dB	-
		1710~2200 MHz	10 dB	-
4	Isolation	450~960 MHz	15 dB	-
		1427~1710 MHz	19 dB	-
		1710~2200 MHz	10 dB	-
		2300~2690 MHz	10 dB	-
5	Port Impedance	50Ω		

Construction

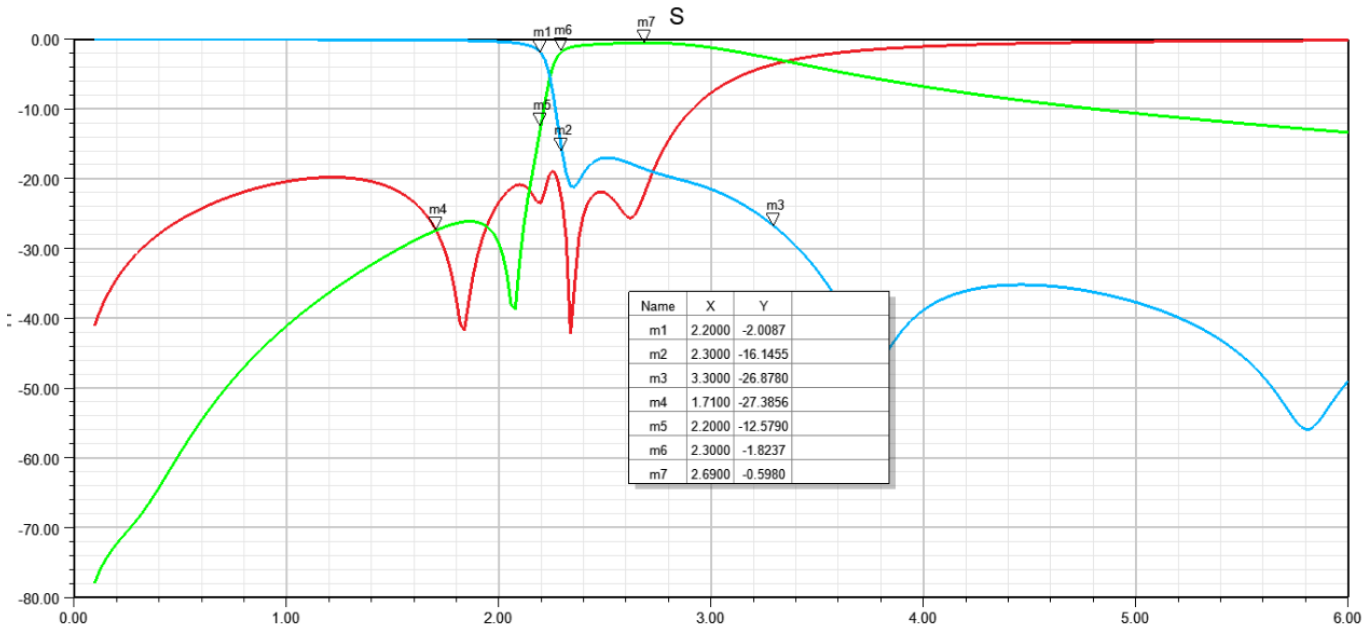


PIN	Connection	PIN	Connection
P1	GND	P4	Higher Port
P2	Common Port	P5	GND
P3	GND	P6	Low Port

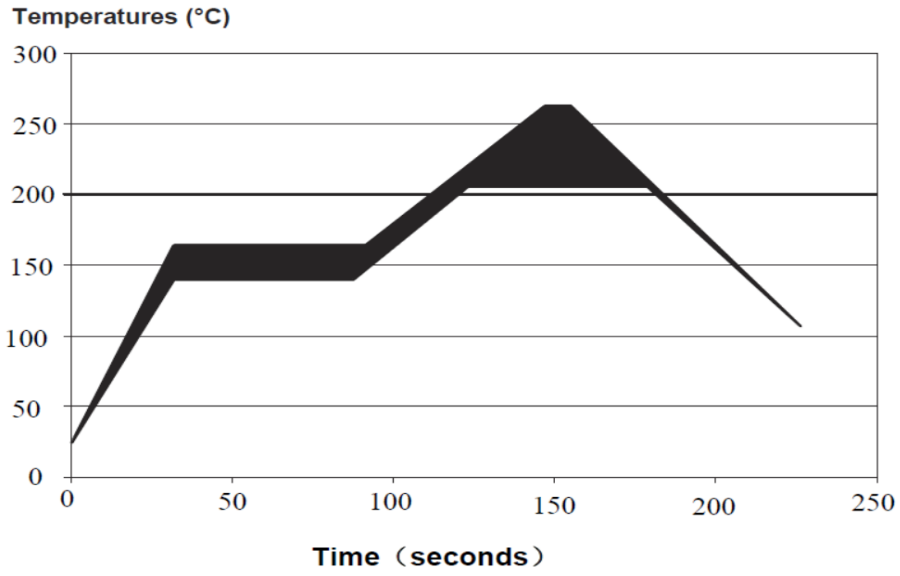
Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50 ± 0.10
	W	2.00 ± 0.10
	T	0.80MAX
	A	0.75± 0.10
	B	0.65 ± 0.15
	C	0.40 ± 0.10
	D	0.53 ± 0.10
	E	0.40 ± 0.05

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

*** After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than12 months, confirm their terminals and solderability before use.**